



PATENT
INTEL/16651

**IN THE UNITED STATES PATENT
AND TRADEMARK OFFICE**

Applicants: Towle et al.

Serial No.: 10/649,240

Filed: August 27, 2003

Assignee: Intel Corporation

For: OPTOELECTRONIC PACKAGES
AND METHODS TO
SIMULTANEOUSLY COUPLE AN
OPTOELECTRONIC CHIP TO A
WAVEGUIDE AND SUBSTRATE

Group Art Unit: Unknown

Examiner: Unknown

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) 
) James A. Flight

) Registration No. 37,622

) Attorney for Applicants

INFORMATION DISCLOSURE STATEMENT

Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

Sir or Madam:

The patents and/or publications listed on the enclosed PTO Form-1449 are submitted pursuant to 37 CFR §§ 1.56, 1.97, and 1.98. Copies of the patents or publications are enclosed.

TIME OF FILING

This information disclosure statement is being filed to the best of the undersigned's knowledge, before the mailing date of a first Office action on the merits. In accordance with 37 CFR §1.97(b), no certification or fee is required.



PRIOR AND RELATED APPLICATIONS

The examiner is respectfully made aware of the following co-pending application which contains subject matter related to this application:

Applicant(s):	Towle et al.
Serial No.	10/664,475
Filing Date:	September 17, 2003
Title:	METHODS AND APPARATUS TO OPTICALLY COUPLE AN OPTOELECTRONIC CHIP TO A WAVEGUIDE
Status:	Pending

METHOD OF PAYMENT

☒ No fee is required.

The Commissioner is authorized to charge any fee deficiency required by this paper, or credit any overpayment, to Deposit Account No. 50-2455. A copy of this paper is enclosed.

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Respectfully submitted,

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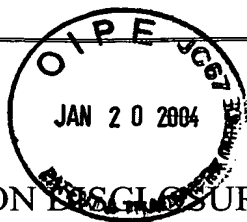
By:


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Attorneys for Intel Corporation

January 14, 2004

Form PTO-1449 (Modified)

U.S. Department of Commerce
Patent and Trademark Office

Atty. Docket No.

INTEL/16651

Serial No.

10/649,240

INFORMATION DISCLOSURE STATEMENT

(Use several sheets if necessary)

Applicant

Towle et al.

Filing Date

8-27-2003

Group Art Unit

Unknown

U.S. PATENT DOCUMENTS

*EXAMINER INITIALS	DOCUMENT NUMBER	ISSUE DATE	NAME	CLASS	SUBCLASS	FILING DATE IF APPROPRIATE

FOREIGN PATENT DOCUMENTS

*Examiner Initials	Document Number	Publication Date	Country	Class	Subclass	Translation Yes No	

OTHER DOCUMENTS (Including Author, Title, Date, Pertinent Pages, etc.)

		Baggs, J; Machon, W; Magill, P; Mis, J; Rinne, G. "Solder Alloy Selection for Flip Chip on Board." International Material and Packaging Society Symposium, Brasleton, Georgia. February 1998. Pages 1-5.
		Bogaerts, W; Bienstman, P; Baets, R. "Sidewall Roughness in Photonic Crystal Slabs: A Comparison of High-Contrast Membranes and Low-Contrast III-V Epitaxial Structures." 11 th International Workshop on Optical Waveguide Theory and Numerical Modelling, April 4-5, 2003, Prague, Czech Republic. Pages 1-4.
		"Polymer Technology Overview." Optical Crosslinks, Incorporated. 2001. Pages 1-10. Retrieved from internet: <URL: http://www.opticalcrosslinks.com/pdf/WebPolymerTECHNOLOGYPlatform.pdf >.
		"Polymer Technology: Performance Data and Design Considerations." Optical Crosslinks, Incorporated. 2001. Pages 1-9. Retrieved from internet: <URL: http://www.opticalcrosslinks.com/pdf/WebPerformanceDataDesignTECHNOLGY.pdf >.

EXAMINER

DATE CONSIDERED

*EXAMINER: Initial if reference considered, whether or not citation is in conformance with MPEP 609; Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.